



# SOT1259

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO3P

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	TO3P
<b>Package type industry code</b>	TO3P
<b>Package style descriptive code</b>	SFM (single-ended flange mount)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	H (heatsink mount)
<b>Issue date</b>	22-10-2014

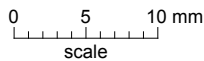
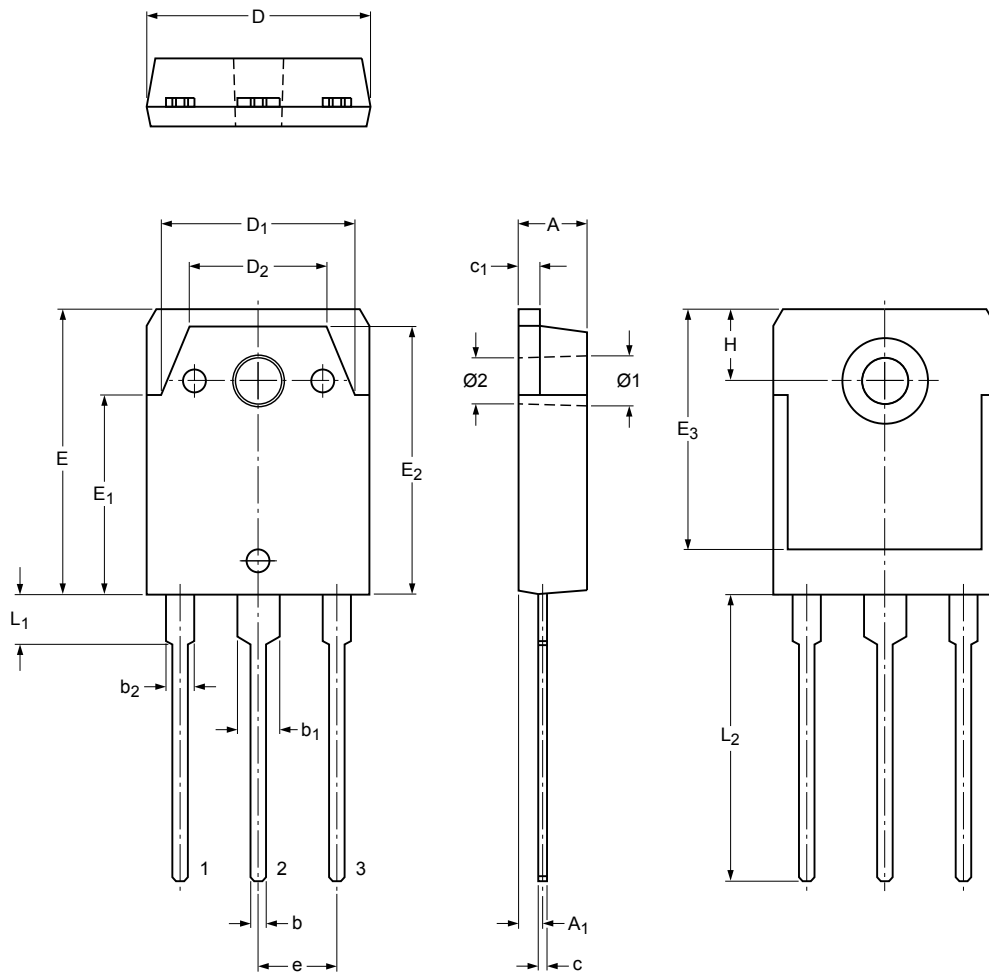
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.4	-	15.6	15.8	mm
E	package width	19.7	-	19.9	20.1	mm
A	seated height	4.6	-	4.8	5	mm
e	nominal pitch	-	-	5.45	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	3	-	



2. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO3P SOT1259



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	c <sub>1</sub>	D	D <sub>1</sub>	D <sub>2</sub>	e	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	H	L <sub>1</sub>	L <sub>2</sub>	Ø1	Ø2
max	5.0	1.6	1.2	3.2	2.2	0.75	1.65	15.8	13.8	9.8		20.1	14.1	18.9	17.06	5.2	3.7	20.3	3.5	3.3
nom											5.45									
min	4.6	1.2	0.8	2.8	1.8	0.55	1.45	15.4	13.4	9.4	(typ)	19.7	13.7	18.5	16.46	4.8	3.3	19.7	3.3	3.1

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1259		TO3P			14-10-21- 14-10-22

Fig. 1. Package outline TO3P (SOT1259)

### 3. Legal information

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## 4. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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